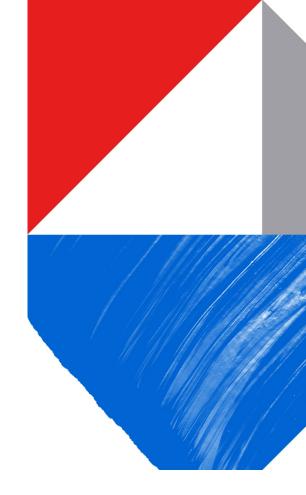
TOSHIBA



Abbreviation Collection

Toshiba Electronic Devices & Storage Corporation

Ver.2 December 2018

* Seal shows our term in the company.

AC	Alternating Current	交流電流
AES	Auger Electron Spectroscopy	オージェ電子分光法
AFM	Atomic Force Microscope	原子間力顕微鏡
AQL	Acceptable Quality Level	合格品質水準
ASIC	Application Specific Integrated	特定用途向けカスタム集積回路
	Circuit	
ATPG	Automatic Test Pattern Generator	テストパターン自動生成
EBテスタ	Electron Beam Tester	電子ビームテスタ
BEM	Breakdown Energy of Metal	金属配線に大電流を流し溶断するまでのエ
		ネルギー量で評価する方式
ВМ	Barrier Metal	バリアメタル
BPSG	Boro Phospho Silicate Glass	硼素リン ケイ酸ガラス
BTI	Bias Temperature Instability	
CAD	Computer Aided Design	コンピュータ支援による設計
CCD	Charge Coupled Device	電荷結合素子
CDM	Charged Device Model	デバイス帯電モデル
CIM	Computer Integrated	コンピュータをベースとした生産管理システム
	Manufacturing	
CL	Contractual Liability	契約責任
CMOS	Complementary Metal-Oxide	相補性金属酸化膜半導体
	Semiconductor	
CMP	Chemical Mechanical Polishing	化学機械研磨法
CTR	Current Transfer Ratio	電流変換効率
CVD	Chemical Vapor Deposition	化学反応による気相成長
DAT	Design Approval Test	設計認定試験
DC	Direct Current	直流電流
DIP	Dual Inline Package	リード・ピンが2直列並行に配置されているパ
		ッケージ
DL	Defect Level	欠陥レベル
DLTS	Deep Level Transient	不純物準位分光評価
	Spectroscopy	
DR	Design Review	設計審査

ECP	Environmentally Conscious Products	環境調和型製品
EBIC	Electron Beam Induced Current	
EEPROM	Electrically Erasable and	記憶内容を電気的に書き換え可能な読み出
	Programmable Read Only Memory	し専用メモリ
EM	ElectroMigration	エレクトロマイグレーション
EPMA	Electron Probe X-ray Micro	
	Analyzer	イザー
EPROM	Erasable and Programmable Read	消去可能な再書き込み可能な読み出し専用
	Only Memory	メモリ
ESD	ElectroStatic Discharge	静電気放電
ESR	Electron Spin Resonance	電子スピン共鳴
FBGA	Fine pitch Ball Grid Array	BGA(パッケージ)種類の1つ
FIB	Focused Ion Beam	
FMEA	Failure Mode and Effects Analysis	故障モード及びその影響度解析
FTA	Fault Tree Analysis	故障の木解析
FT-IR	Fourier Transform Infrared	
	Spectroscopy	
НВМ	Human Body Model	人体帯電モデル
HCI	Hot Carrier Injection	
IC	Integrated Circuit	集積回路
IGBT	Insulated Gate Bipolar Transistor	 絶縁ゲート型バイポーラトランジスタ
ISS	Ion Scattering Spectroscopy	
LCC	Leadless Chip Carrier package	リードのない小型、高密度用パッケージ
LED	Light Emitting Diode	
LEELS	Low Energy Electronic Loss	 低速電子エネルギ−損失分光
	Spectroscopy	
LSI	Large Scale Integration	大規模集積回路
LQFP	Low profile Quad Flat Package	QFP(パッケージ)種類の 1 つ
LTPD	Lot Tolerance Percent Defective	Lot 許容不良率

MSDSMaterial Safety Data Sheet化学物質安全性データシートMTBFMean Time Between Failures平均故障間隔時間MTFMedian Time to Failureメジアン故障寿命MTTFMean Time To Failure平均故障寿命NBTINegative Bias Temperature負バイアス不安定性	
MTFMedian Time to Failureメジアン故障寿命MTTFMean Time To Failure平均故障寿命	
MTTF Mean Time To Failure 平均故障寿命	
NBTI Negative Bias Temperature 負バイアス不安定性	
regative bids remperators	
Instability	
OBIC Optical Beam Induced Current 光励起電流法	
OBIRCH Optical Beam Induced Resistance 光ビーム加熱抵抗変化検出法((オバーク)
CHange	
ONO Oxide Nitride Oxide SiO ₂ /SiN/SiO ₂ (ONO)の3層	構造
OSF Oxidation induced Stacking Fault 酸化誘起積層欠陥	
PAT Production Approval Test 量產品質認定試験	
PCB Printed Circuit Board プリント回路基板	
PDA Personal Digital Assistant 携帯情報端末	
PEM Photo Emission Microscopy エミッション顕微鏡	
PEP Photo Etching Process 写真蝕刻工程	
PGA Pin Grid Array package パッケージの下面からリードピンを	取り出すLSI
パッケージの1つ	
PIXE Particle Induced X-ray Emission 粒子線励起X線	
PL Product Liability 製造物責任	
QAT Quality Approval Test 量產試作品認定試験	
QFP Quad Flat Package 四方にリードのあるフラットパッケー	ージ
RBS Rutherford Backscattering ラザフォード後方散乱	
Spectrometry	
RIE Reactive Ion Etching 反応性イオンエッチング	
SCM Supply Chain Management サプライチェーンマネジメント	
SEM Scanning Electron Microscope 走査電子顕微鏡	
SILC Stress Induced Leakage Current	
SIMS Secondary Ion Mass Spectrometry 二次イオン質量分析装置	
SIP Single In line Package ピン配列が片側一列だけになって	ているICパッケ
SM Stress Migration ストレスマイグレーション	
SMD Surface Mounted Devices 面実装デバイス	

SoC	System on Chip	
SPC	Statistical Process Control	統計的品質管理
SPM	Scanning Probe Microscope	走査形プローブ顕微鏡
SSOP	Shrink SOP (Small Outline	SOP(パッケージ)種類の1つ
	Package)	
STM	Scanning Tunneling Microscope	走査形トンネル顕微鏡
TAT	Turn Around Time	納期、応答時間
TCP	Tape Carrier Package	ICチップをテープフィルムと接続し、樹脂を封止
		するTAB技術を用いたパッケージ
TDDB	Time Dependent Dielectric	経時絶縁破壊.酸化膜故障予測手段
	Breakdown	
TEG	Test Element Group	
TEM	Transmission Electron Microscope	透過電子顕微鏡
TOF-SIMS	Time Of Flight Secondary Ion Mass	飛行時間型2次イオン質量分析装置
	Spectrometry	
TPM	Total Productive Maintenance	全員参加の生産保全
TTF	Time To Failure	
UPS	Ultra-violet Photoelectron	紫外光励起光電子分光
	Spectroscopy	
VPS	Vapor Phase Soldering	蒸気相はんだ付け
XPS	X-ray Photoelectron Spectroscopy	X線光電子分光
	<u> </u>	

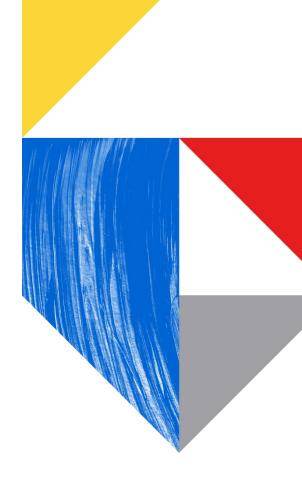
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